

REVISION HISTORY				
REV	DESCRIPTION	ORIGINATOR	INCORPORATOR	DATE
00	INITIAL RELEASE	YESH	YESH	03/21/08

7.

REFERENCE SPECIFICATIONS:
A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
B. AAWW SPEC #001-0519-2062: MARKING.

6.

PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5.

DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4.

THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BUMPS IS 529.

3.

THE MAXIMUM SOLDER BALL MATRIX SIZE IS 23 X 23.

2.

THE BASIC SOLDER BUMP GRID PITCH IS 0.30mm.

1.

ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.

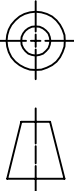
NOTES: UNLESS OTHERWISE SPECIFIED

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DIMENSIONS ARE IN MILLIMETERS

DECIMAL
X.X ±0.1
X.XX ±0.05
X.XXX ±0.030

INTERPRET DIM AND TOL PER
ASME Y14.5M - 1994

THIRD ANGLE
PROJECTION



APPROVALS

DESIGNED
YESH
CHECKED
YUYOON

DATE
03/19/08
03/19/08



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TITLE
PACKAGE OUTLINE - MAF, 23 X 23 MATRIX,
8.00mm X 8.00mm X 1.00mmMAX, 0.70mm MOLD CAP,
0.18mm BALL, 0.30mm PITCH, LAMINATE SUBSTRATE, AWW

SIZE
A3

SID NUMBER
N/A

DWG NUMBER
351372

REV
00

PRODUCT MANAGER
JSCAN

RELEASED
SMSO

DATE
03/21/08

STRIP DWG NUMBER/REV
N/A

PKG OUTLINE DWG NO.
N/A

SCALE
NONE

SHEET
1 OF 3

FINISH
N/A

DO NOT SCALE DRAWING